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	Specification	
Part Number:		
Version:		
Date:		
	Revision	

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1.General Specification

The Features is described as follow:

- Module dimension: 98.0 x 60.0 x 13.6 (max.) mm
- View area: 77.0 x 25.2 mm
- Active area: 70.4 x 20.8 mm
- Number of Characters: 20 characters x 4 Lines
- Dot size: 0.55 x 0.55 mm
- Dot pitch: 0.60 x 0.60 mm
- Character size: 2.95 x 4.75 mm
- Character pitch: 3.55 x 5.35 mm
- LCD type: VA Negative Transmissive
- Duty: 1/16
- View direction: 12 o'clock
- Backlight Type: LED, High light White COLUTE SUPPLY
- IC:ST7066U

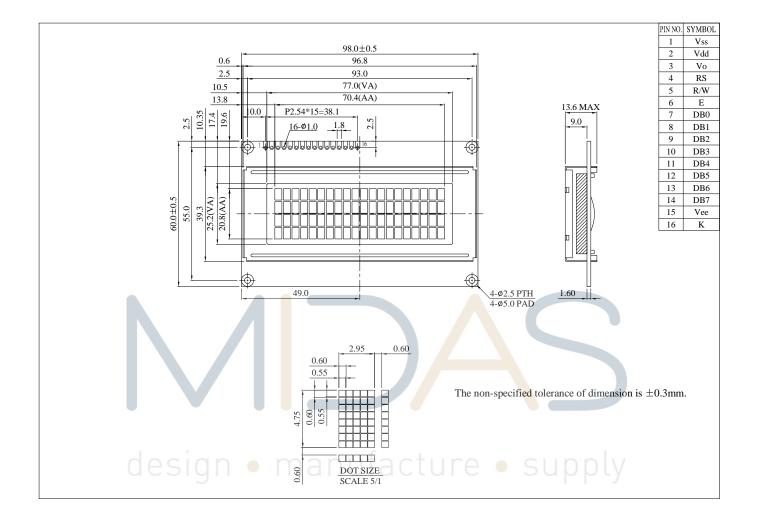
Midas LCD Part Number System

МС	COG	132033	Α	*	6	W	*	*	-	S	Ν	т	L	w	*	*
1	2	3	4	5	6	7	8	9	-	10	11	12	13	14	15	16
1	=	MC: Midas Con	npone	nts												
2	=	Blank: COB (ch	ip on	board)	COG	: chip on	glass									
3	=	No of dots		(e.g. 240	064 = 2	240 x 64	dots)	(e.g. 210	505 = 2	x 16 5n	nm C.H.)				
4	=	Series														
5	=	Series Variant:		A to Z –	see ad	dendum										
6	=	3: 3 o'clock		6: 6 o'cl	ock	9 : 9	9 o'cloc	k	12 : 1	12 o'cloc	k					
7	=	S : Normal (0 to	+ 50	deg C)	W: Wid	le temp. ((-20 to	+ 70 deş	g C) X	: Extend	ed temp	(-30 + 8	30 Deg (2)		
8	=	Character Set														
9	-	Blank 9.5 2 8.9 3 7.8 4 7.8 5 9.5 6 7 n 7 7 4 9 6.4 A 5.5 D 6.0 E 5.00 F 4.7	plified g 5 (G d) (Er esec (s English nglish, renglish, where a p of B mm / mm mm mm mm	(Graphi raphic D nglish/Ge pecial) /Scandin /Greek) /Scandin	c Displa isplays rman/Fr avian) avian/Ic avian/Ic avian/Ic bop of	only) rench/Gro elandic)	on (via and 2) mon rate mon rate mon rate mon rate mon rate rate rate mon	Arrra Edge Arr Arr Arr Arr Arr Edg Edg Edg Edg Edg Edg Edg Edg Edg Edg	e Lit ray ray ray ray ray ray ray ge ge ge ge ge ge ge ge			S			y	
10	=	T: TN S : STN	B: STI	N Blue (G: STN	Grey F:	FSTN	F2: FFS7	"N Z: Z	Zero Pov	ver (Bi-S	stable)				
11	=	P: Positive N: N	Vegativ	/e												
12	=	R: Reflective M	: Tran	smissive	T: Tra	nsflective	2									
13	=	Backlight: Blan	k: Refl	ective L	: LED											
14	=	Backlight Colou	I T:	Y: Yellov	v-Green	W: Whi	ite B: I	Blue R:	Red A	: Amber	0: Ora	inge G: (Green R	GB: R.G.	B.	
		lf Z (Zero Powe	er):	WB: Wh	ite on b	olue GB	: Green	on blac	k YB :	Yellow	on black	ΥΡΒ: Υ	ellow on	ı pink ar	nd/or blu	e
15	=	Driver Chip:		Blank: St	tandard]: ŀ	ст:	Toshiba	T6963	3C A:	Avant S	AP1024B	R: R	aio RA8	835	
16	=	Voltage Variant	:: e.g. 3	3 = 3v												
												•				

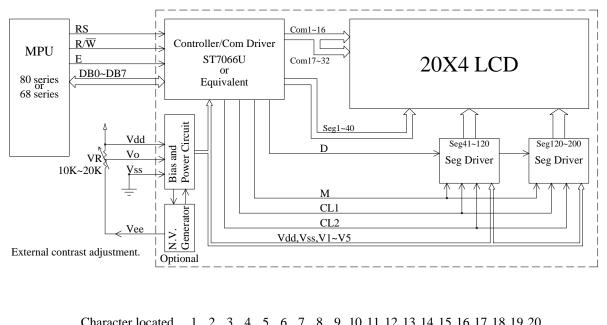
F/Displays/Midas Brand/Midas LCD Part Number System 2 March 2011.doc

3.Interface Pin Function

Pin No.	Symbol	Level	Description
1	V_{SS}	0V	Ground
2	V_{DD}	5.0V	Supply Voltage for logic
3	VO	(Variable)	Operating voltage for LCD
4	RS	H/L	H: DATA, L: Instruction code
5	R/W	H/L	H: Read (Module> MPU) L: Write(MPU> Module)
6	E	H,H→L	Chip enable signal
7	DB0	H/L	Data bus line
8	DB1	H/L	Data bus line
9	DB2	H/L	Data bus line
10	DB3	H/L	Data bus line
11	DB4	H/L	Data bus line
12	DB5	H/L	Data bus line
13	DB6	H/L	Data bus line
14	DB7	H/L	Data bus line
15	Vee		Negative Voltage Output
16	К	_	Power supply for B/L -



4.Contour Drawing & Block Diagram



Character located	1	2	3	4	5	0	/	ð	9	10	11	12	13	14	15	10	17	18	19	20
DDRAM address	00	01	02	03	04	05	06	07	08	09	0A	0 B	0C	0D	0E	0F	10	11	12	13
DDRAM address	40	41	42	43	44	45	46	47	48	49	4A	4B	4C	4D	4E	4F	50	51	52	53
DDRAM address	14	15	16	17	18	19	1A	1B	1C	1D	1E	1F	20	21	22	23	24	25	26	27
DDRAM address	54	55	56	57	58	59	5A	5B	5C	5D	5E	5F	60	61	62	63	64	65	66	67
																	_			

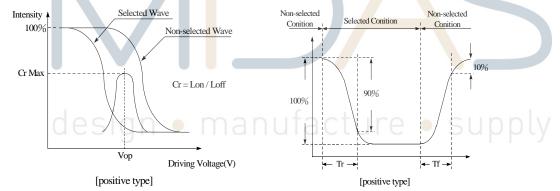
Upper 4bit Lower 4bit	LLLL	LLHL	LLHH	LHLL	LHLH	LHHH	HLLL	HLLH	HLHL	нгнн	HHLL	HHLH	
LLLL	CG RAM (1)												
LLLH	(2)												
LLHL	(3)												
LLHH	(4)												
LHLL	(5)												
LHLH	(6)												
LHHL	(7)												
LHHH	(8)												
HLLL	(1)												
HLLH	(2)												
HLHL	(3)												
HLHH	(4)												
HHLL	(5)												
HHLH	(6)												
HHHL	(7)												
нннн	(8)												

6.Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
	θ	CR≧10	_	60	_	ψ= 180°
View Angle	θ	CR≧10		25	_	ψ= 0°
View Angle	θ	CR≧10		40	_	ψ= 90°
	θ	CR≧10		40	_	ψ= 270°
Contrast Ratio	CR		10			
Deenenge Time	T rise			300	350	ms
Response Time	T fall			300	350	ms

Definition of Operation Voltage (Vop)

Definition of Response Time (Tr, Tf)



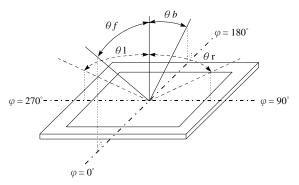
Conditions :

Operating Voltage : Vop

Viewing Angle(θ , $\phi)$: 0° , ~ 0°

Frame Frequency : 64 HZ Driving Waveform : 1/N duty , 1/a bias

Definition of viewing angle(CR \geq 2)



7. Absolute Maximum Ratings

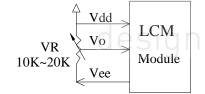
ltem	Symbol	Min	Тур	Max	Unit
Operating Temperature	T _{OP}	-20	—	+70	°C
Storage Temperature	T _{ST}	-30	_	+80	°C
Input Voltage	VI	V _{SS}	_	V_{DD}	V
Supply Voltage For Logic	Vdd-V _{SS}	-0.3	_	7	V
Supply Voltage For LCD	V _{DD} -V _o	-0.3	_	13	V



8.Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	V_{DD} - V_{SS}	_	4.5	5.0	5.5	V
Supply Voltage For LCD		Ta=-20 ℃	_		_	V
*Note	V_{DD} - V_0	Ta=25 ℃	6.2	6.5	6.8	V
		Ta=70 ℃	—	—	—	V
Input High Volt.	V _{IH}		$0.7 V_{DD}$		V_{DD}	V
Input Low Volt.	V _{IL}		V _{SS}		0.6	V
Output High Volt.	V _{он}		3.9	_	Vdd	V
Output Low Volt.	V _{OL}	_	0		0.4	V
Supply Current	I _{DD}	$V_{DD}=5.0V$	2.0	2.5	3.0	mA

* Note: Please design the VOP adjustment circuit on customer's main board



manufacture • supply

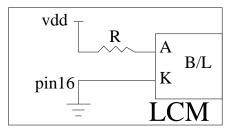
9.Backlight Information

Specification

PARAMETER	SYMBOL	MIN	ТҮР	МАХ	UNIT	TEST CONDITION
Supply Current	ILED	_	128	160	mA	V=5.0V
Supply Voltage	v	4.9	5.0	5.1	v	_
Reverse Voltage	VR	_	_	5	v	_
Luminance (Without LCD)	IV	960	1200	_	CD/M ²	ILED=128mA
LED Life Time (For Reference only)	-/	_	20K			ILED=128mA 25℃,50-60%RH, (Note 1)
Color	White(hig	h light)				

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Drive from Vdd, Pin 16



10.Reliability

Content of Reliability Test (Wide temperature, -20°C~70°C)

Environmental Test											
Test Item	Content of Test	Test Condition	Note								
High Temperature storage	Endurance test applying the high storage temperature for a long time.	200hrs	2								
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30℃ 200hrs	1,2								
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70℃ 200hrs									
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20℃ 200hrs	1								
High Temperature/ Humidity storage	The module should be allowed to stand at $60^{\circ}C$,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C ,90%RH 96hrs	1,2								
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20°C 25°C 70°C 30min 5min 30min 1 cycle	-20℃ /70 ℃ 10 cycles									
desig Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude : 1.5mm Vibration Frequency : 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3								
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5kΩ CS=100pF 1 time									

Note1: No dew condensation to be observed.

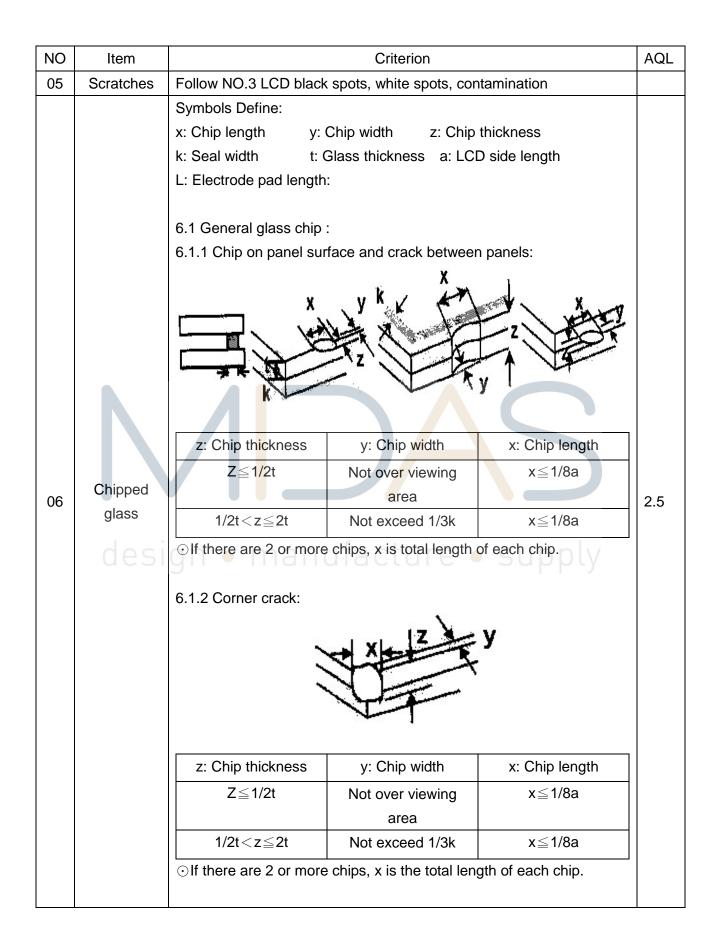
Note2: The function test shall be conducted after 4 hours storage at the normal

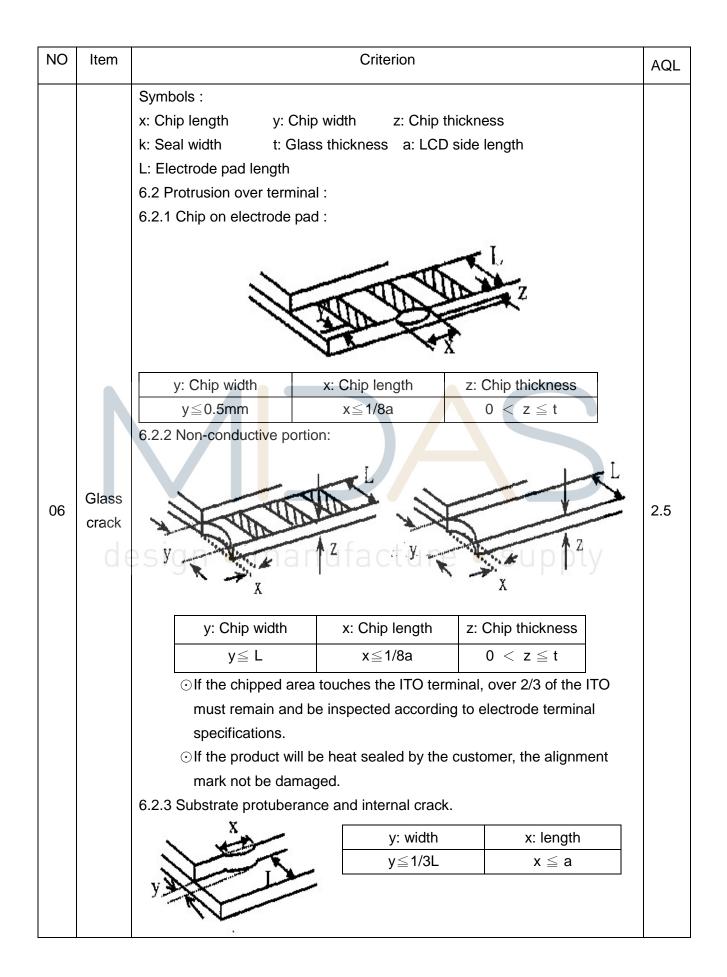
Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

11.Inspection specification

NO	Item			Criterion		AQL				
01	Electrical Testing	1.3 Display malf 1.4 No function 1.5 Current cons 1.6 LCD viewing 1.7 Mixed produ	defect. 1.2 Missing character , dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect.							
02	Black or white spots on LCD (display only)	three white c	 2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm 							
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type $\Phi = (x + y) / $ X	2 ↓ ▼Y ∩uf	SIZE $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi$	Acceptable Q TY Accept no dense 2 1 0 Acceptable Q TY Accept no dense 2 As round type	2.5				
04	Polarizer bubbles	If bubbles are vi judge using blac specifications, n to find, must che specify direction	ck spot ot easy eck in	Size Φ $\Phi \leq 0.20$ $0.20 < \Phi \leq 0.50$ $0.50 < \Phi \leq 1.00$ $1.00 < \Phi$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3 3	2.5				





NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB.COB	 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB X * Y<=2mm2 	 2.5 2.5 0.65 2.5 0.65 2.5 0.65 2.5 2.5 2.5
11	Soldering	 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	 2.5 2.5 2.5 0.65

NO	Item	Criterion			
	Item	 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface 	AQL 2.5 0.65 2.5 2.5 2.5		
12	General appearance	 12.5 The upperhiost edge of the protective stip on the interface pin to pin must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 LCD pin loose or missing pins. 			
		 12.0 Product packaging must the same as specified on packaging specification sheet. 12.11 Product dimension and structure must conform to product specification sheet. 12.12 Visual defect outside of VA is not considered to be rejection 			

12.Precautions in use of LCD Modules

- (1)Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6)Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8) T aaæ have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors,capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9Dǐ 葡密 have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, T 範密 have the right to modify the version.)

13.Material List of Components for RoHs

1. T aa hereby declares that all of or part of products (with the mark

"#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A : The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs				
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm				
Above limited value is set up according to RoHS.										

2.Process for RoHS requirement :

- (1) Use the Sn/Ag/Cu soldering surface ; the surface of Pb-free solder is rougher than we used before.
- (2) Heat-resistance temp. :

Reflow : 250°C,30 seconds Max. ;

Connector soldering wave or hand soldering : 320 $^\circ\!\mathrm{C}$, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235 \pm 5°C ;

Recommended customer's soldering temp. of connector : $280^\circ\!\mathrm{C}$, 3 seconds.

14.Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5℃ and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.

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